

Application No.: Unassi  
Applicant: Dershem, et. al.  
Filed: Herewith  
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PATENT  
Attorney Docket No.: QUANT1190-3  
(028248-1010)

47. A maleimide-containing compound comprising one or more maleimide groups attached to an alkyl or alkylene linkage capable of curing at a temperature of less than about 200°C in a period of time of about 0.25 minutes up to about 2 minutes.

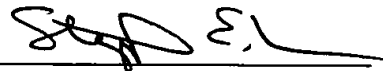
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48. A maleimide composition comprising a maleimide-containing curable component which when dispensed between a 300 x 300 mil silica die and a Ag coated lead frame as a 1 mil bondline and cured for 1 minute at a temperature of about 200°C, demonstrates an initial adhesion value of at least 115 lbs and a post pressure cooker adhesion of at least 83 lbs.

#### REMARKS

By the present communication, claims 46-48 have been introduced to define Applicants' invention with greater particularity. No new matter is introduced by the present amendment as the new claim language is fully supported by the specification and original claims. In addition, claims 1-45 have been cancelled without prejudice. Thus, upon entry of the amendment, claims 46-48 are pending.

In view of the above amendments and remarks, prompt consideration and favorable action on all claims are respectfully requested. In the event any matters remain to be resolved in view of this communication, the Examiner is encouraged to call the undersigned so that a prompt disposition of this application can be achieved.

Respectfully submitted,



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